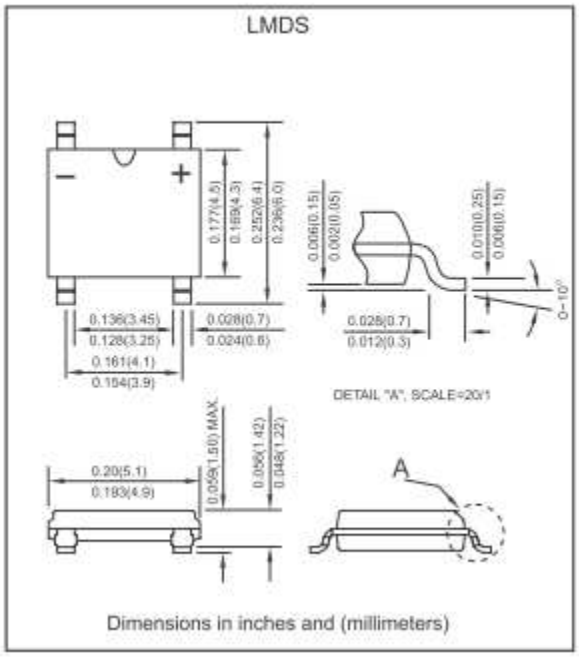
Features

- ◆ Glass passivated junction
- ◆ Ideal for printed circuit board
- ◆ Reliable low cost construction utilizing molded plastic technique
- ◆ High temperature soldering guaranteed: 260℃ / 10 seconds / 0.375" (9.5mm) lead length at 5 lbs., (2.3 kg) tension
- ◆ High surge current capability
- ◆ Suffix "-H" indicates Halogen-free part, ex.ECCBRABS2-H.

Package outline



Mechanical Data

- ◆ Epoxy:UL94-V0 rated flame retardant
- ◆ Case : Molded plastic, LMDS
- ◆ Terminals : Solder plated, solderable per MIL-STD-202, Method 208
- ◆ Polarity : marked on body
- ◆ Mounting Position : Any
- ◆ Weight : Approximated 0.0992 gram

Maximum ratings and Electrical Characteristics (At T_A=25 ℃ unless otherwise noted)

PARAMETER	Conditions	Symbol	Min.	Typ.	Max.	UNIT
Forward rectified current	On glass-epoxy P.C.B. On aluminum substrate	I_O			0.8 1.0	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	I_{FSM}			30	A
Reverse current	V_R= V_{RRM} ,T_J =25℃	I_R			10	μA
	V_R= V_{RRM} ,T_J =125℃				500	
Thermal resistance	Junction to Lead On aluminum substrate On Glass-Epoxy substrate	$R_{\theta JL}$ $R_{\theta JA}$		25 62.5 80		℃/W
Rating for fusing	t< 8.3 ms	I^2t			3.7	A^2S
Storage Temperature		T_{STG}	-55		+150	℃

Part No	V_{RRM}*1 (V)	V_{RRM}*2 (V)	V_{RRM}*3 (V)	V_{RRM}*4 (V)	Operating temperature TJ,(℃)
ECCBRABS2	200	140	200	0.95	-55℃~+150℃
ECCBRABS4	400	280	400		
ECCBRABS6	600	420	600		
ECCBRABS8	800	560	800		
ECCBRABS10	1000	700	1000		

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage @I_F=0.4A

Rating and characteristic curves (ECCBRABS2~ECCBRABS10)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

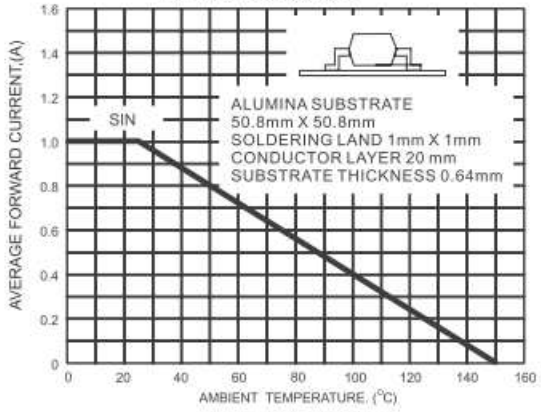


FIG.2-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

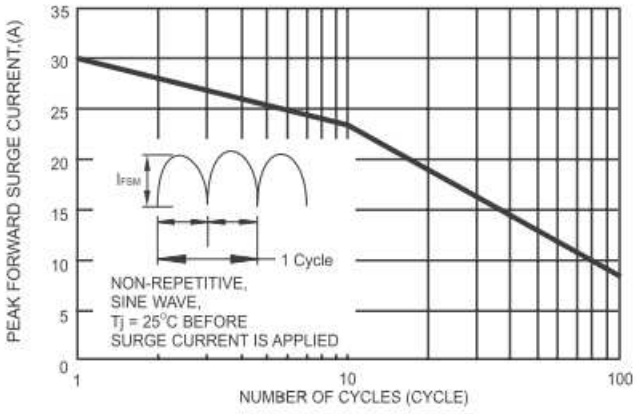


FIG.3-TYPICAL FORWARD CHARACTERISTICS

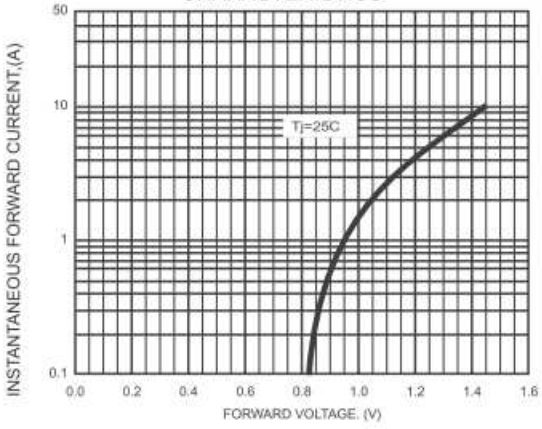
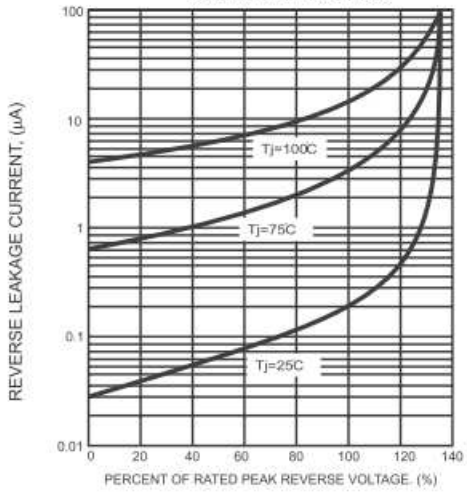
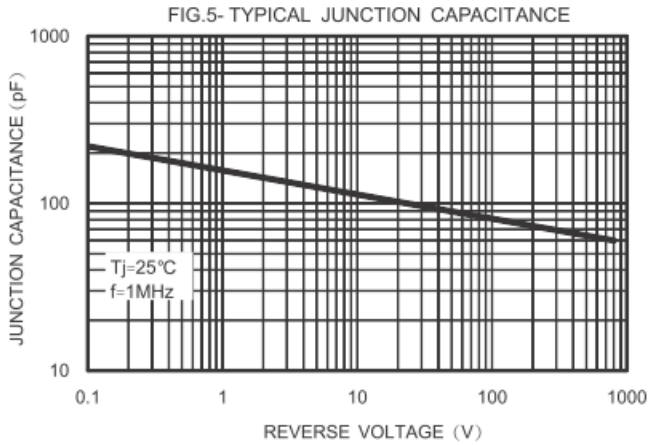
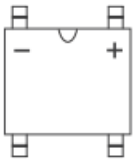
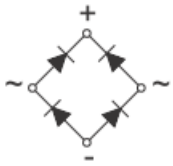


FIG.4-TYPICAL REVERSE CHARACTERISTICS





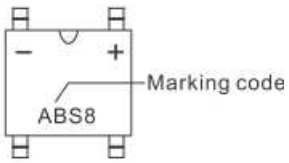
Pinning information

Simplified outline	Symbol
	

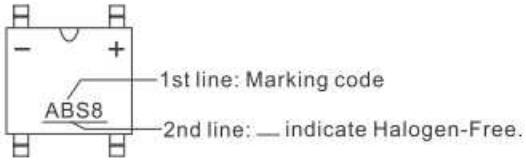
Marking

Part No	Marking
ECCBRABS2 / ECCBRABS2-H	ABS2
ECCBRABS4 / ECCBRABS4-H	ABS4
ECCBRABS6 / ECCBRABS6-H	ABS6
ECCBRABS8 / ECCBRABS8-H	ABS8
ECCBRABS10 / ECCBRABS10-H	ABS10

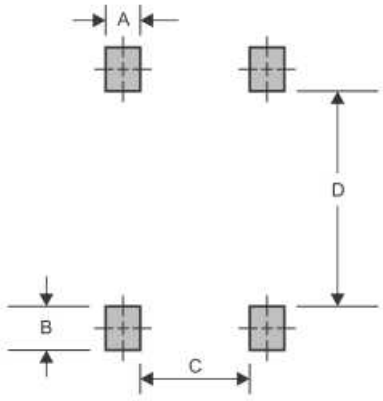
1. For Halogen Device



2. For Halogen-free Device



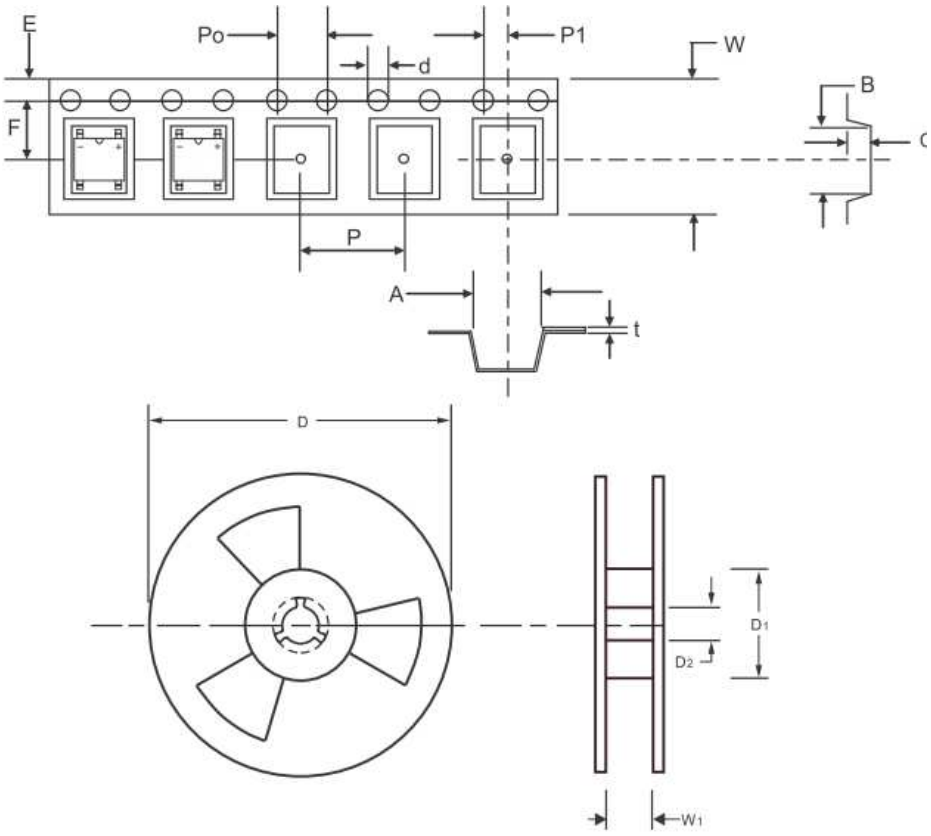
Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D
LMDS	0.024 (0.60)	0.024 (0.60)	0.132 (3.35)	0.193 (4.90)

Packing information



unit:mm

Item	Symbol	Tolerance	LMDS
Carrier width	A	0.1	5.31
Carrier length	B	0.1	6.68
Carrier depth	C	0.1	1.60
Sprocket hole	d	0.05	1.55
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D_1	min	50.00
7" Reel outside diameter	D	2.0	-
7" Reel inner diameter	D_1	min	-
Feed hole diameter	D_2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.05	5.50
Punch hole pitch	P	0.1	8.00
Sprocket hole pitch	P_0	0.1	4.00
Embossment center	P_1	0.05	2.00
Overall tape thickness	t	0.1	0.30
Tape width	W	0.3	12.00
Reel width	W_1	1.0	12~14.4

Note:Devices are packed in accor dance with EIA standar RS-481-A and specifications listed above.

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA. (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
LMDS	13"	5,000	8.0	10,000	337*337*37	330	350*330*360	80,000	19.0